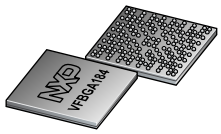

SOT2172-1

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

14 April 2022 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA184
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-12-2021
Manufacturer package code	98ASA01888D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
seated height	-	0.86	0.98	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	184	-	

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

2 Package outline

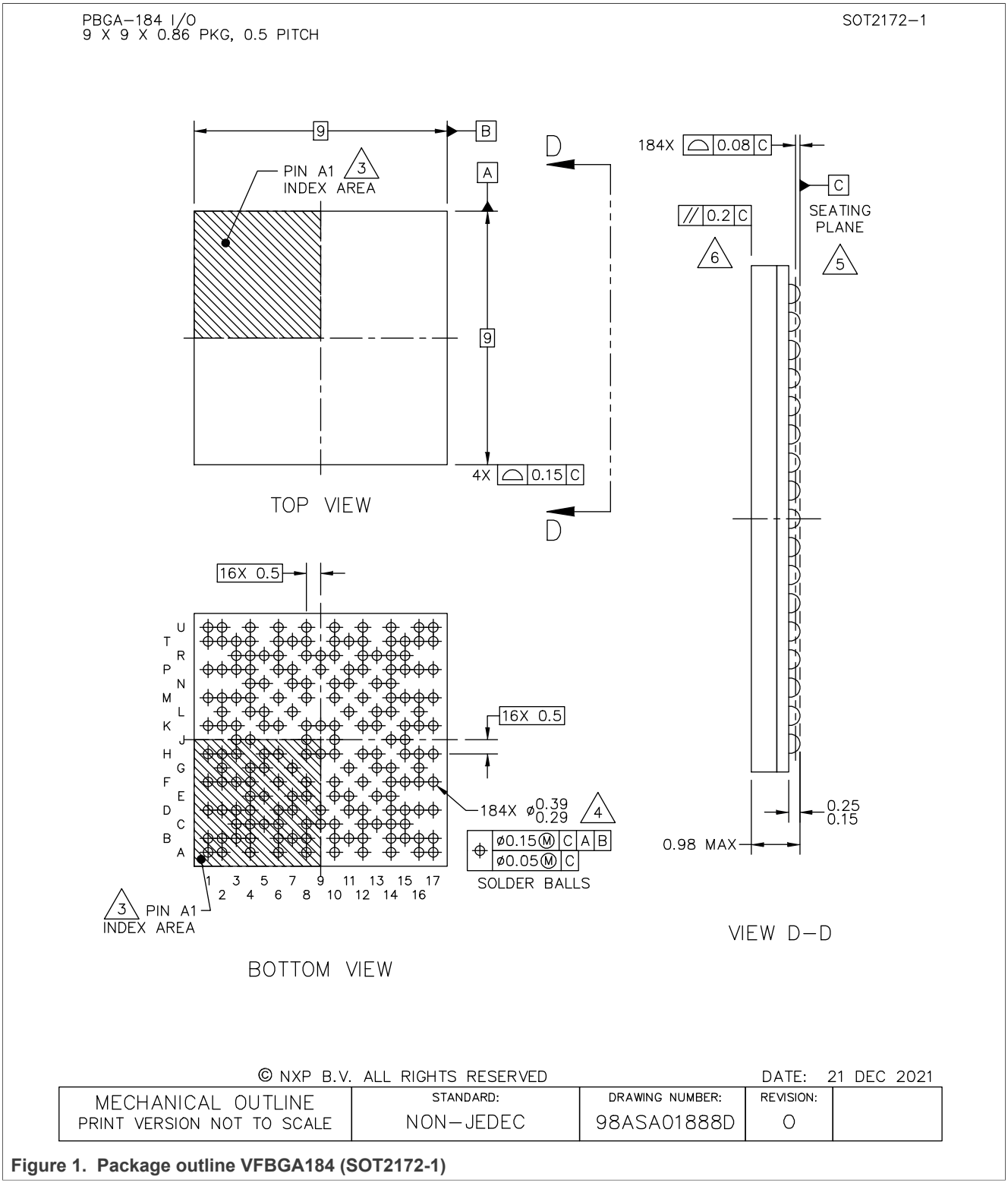

Figure 1. Package outline VFBGA184 (SOT2172-1)

3 Soldering

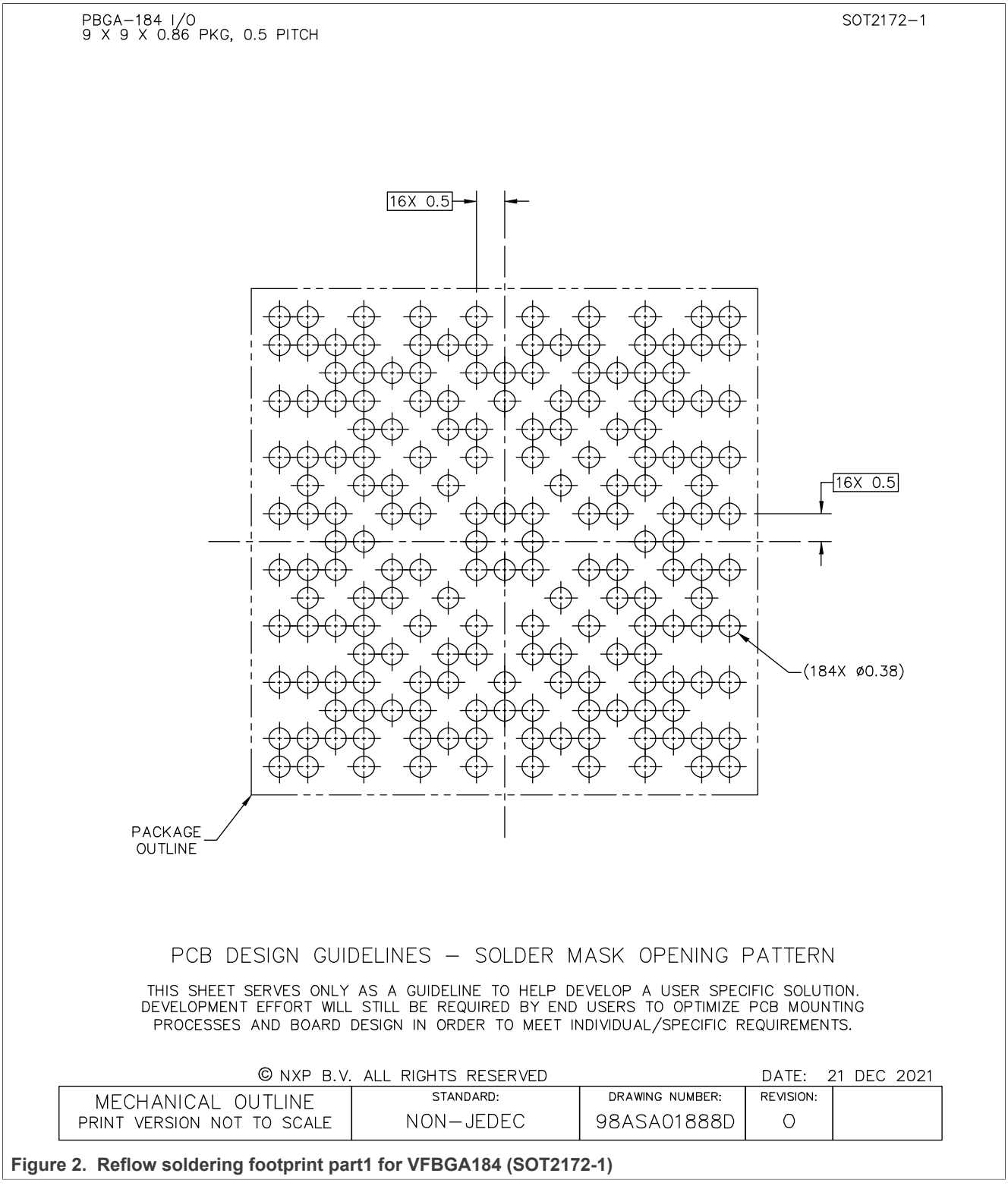

Figure 2. Reflow soldering footprint part1 for VFBGA184 (SOT2172-1)

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

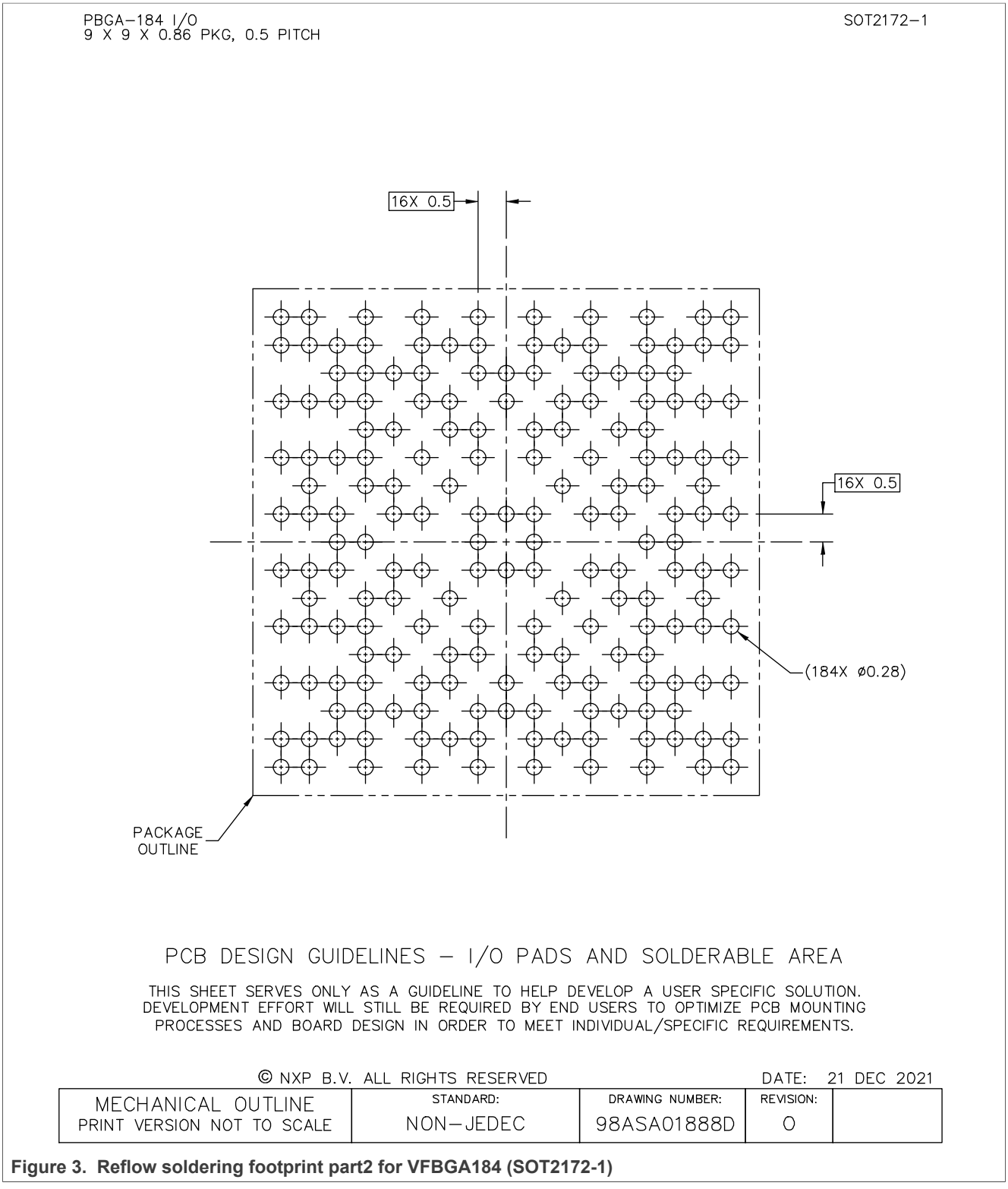

Figure 3. Reflow soldering footprint part2 for VFBGA184 (SOT2172-1)

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

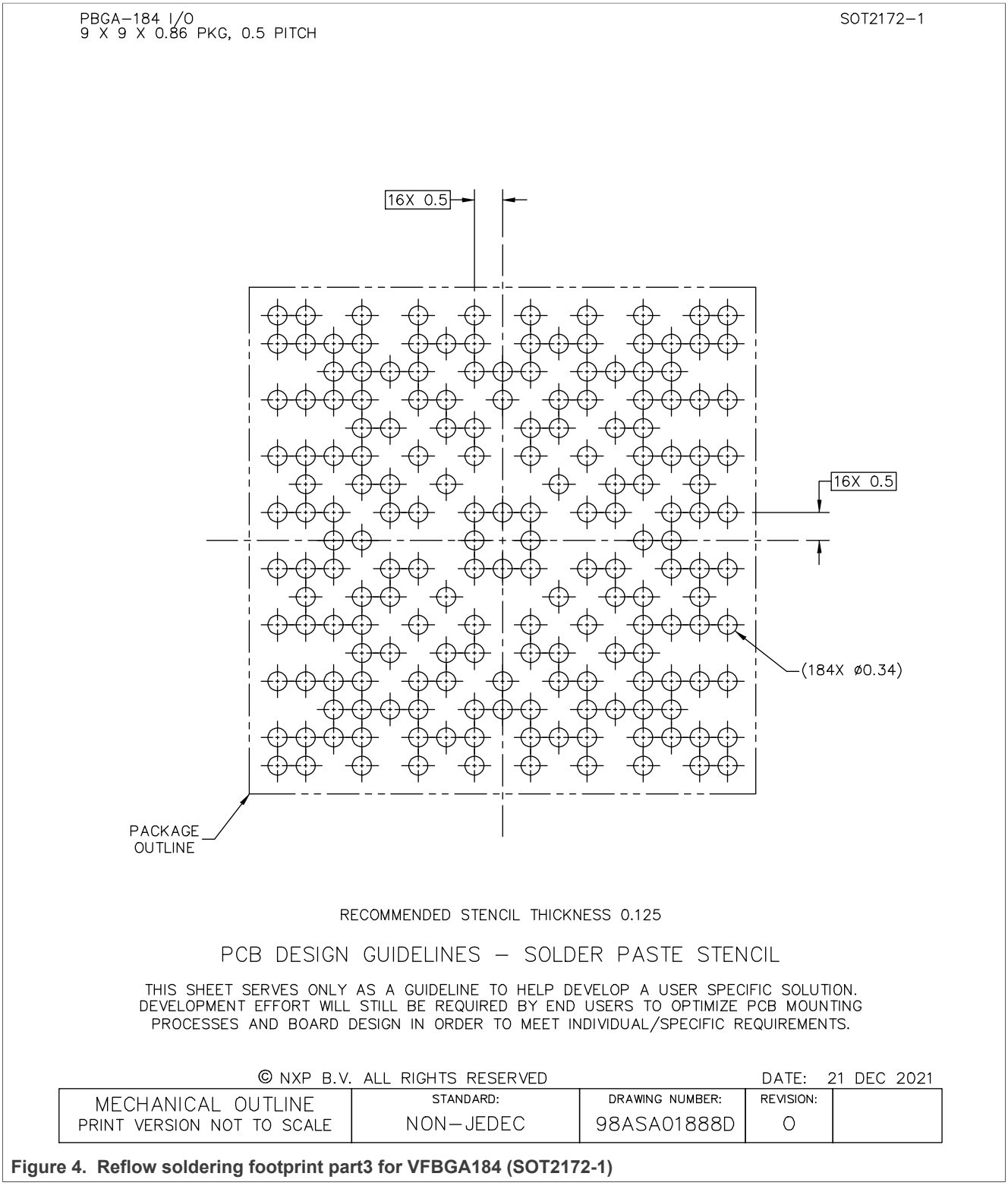

Figure 4. Reflow soldering footprint part3 for VFBGA184 (SOT2172-1)

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

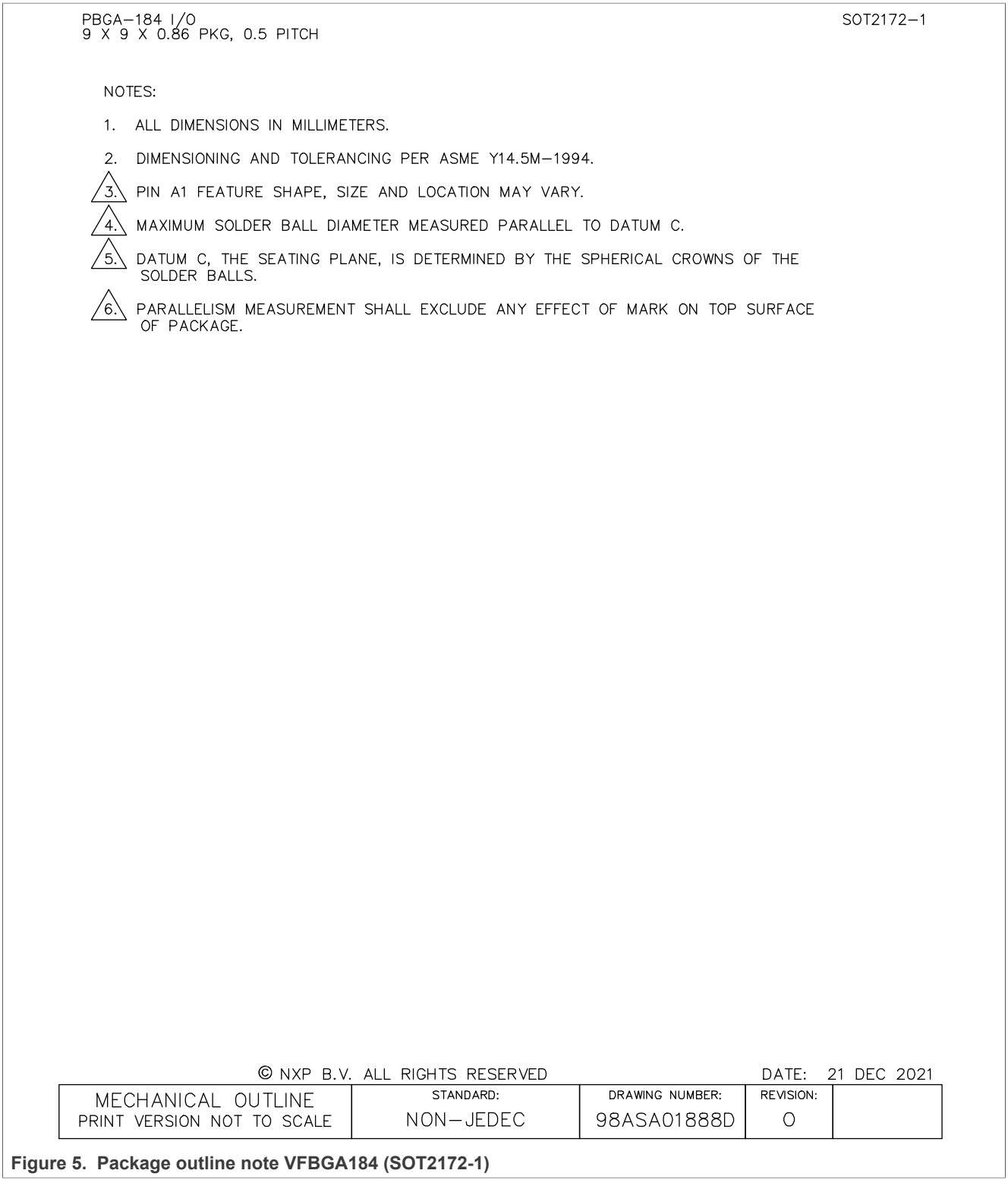

Figure 5. Package outline note VFBGA184 (SOT2172-1)

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SOT2172-1

VFBGA184, very thin fine-pitch ball grid array package, 184 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.86 mm body

Contents

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Date of release: 14 April 2022